EMI Ferrite Bead



BBFY Series



Overview

EMI ferrite beads are made of ferrite material, which can block high-frequency noise while allowing required signals to pass through, providing high impedance and noise attenuation to improve signal integrity/efficiency and reduce power loss.

Benefits

- 1. Compliance with EMI regulations.
- 2. Reduced power loss and improved system efficiency
- 3. Operating temperature range: -55 ~ +125°C
- 4. Improved signal integrity

Applications

- 1. Wearable Devices
- 2. Industrial
- 3. Communications
- 4. Consumer Electronics

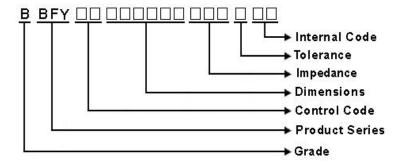
Product Information

Series	Size Code (JIS/EIA)	Impedance (Ω)
BBFY	1005/0402	120 ~ 1000





- 1 Scope: This specification applies to MULTILAYER FERRITE CHIP BEADS
- 2 Part Numbering:



3 Rating:

Operating Temperature: $-55\% \sim 125\%$ (Including self - temperature rise)

Storage Temperature: $-55^{\circ}\text{C} \sim 125^{\circ}\text{C}(\text{after PCB})$

- 5 °C~ 4 0 °C, Humidity 4 0 %~ 7 0 % (before PCB)

4 Marking:

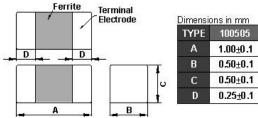
No Marking

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH



6 Configuration and Dimensions:



Net Weight (grms)	
Size Code	Net Weight (grms)
100505	0.0014

7 Electrical Characteristics:

Part No.	Impedance (Ω)±25%	Impedance (Ω)±40%	Test Freq. (MHZ)	RDC (Ω)Max.	Rated Current (mA)Max.	
BBFY00100505121YHP	120	150	100/1000	0.095	1500	
BBFY00100505221YHP	220	270	100/1000	0.28	700	

NOTE: tolerance Y=±25%

1. Operating temperature range - 5 5 $^{\circ}$ C ~ 1 2 5 $^{\circ}$ C(Including self - temperature rise)

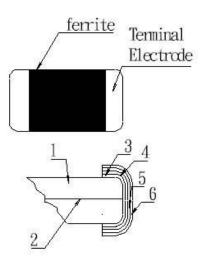
2.Rate Current : Applied the current to coils, the temperature rise shall not be more than 30°C

3.Impedance Test OSC @200mV



8 BBFY00100505 Series

8.1 Construction:



8.2 Material List:

No	Part	Material
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn

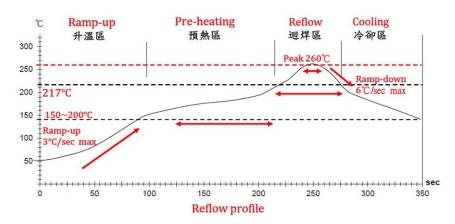


9 Reliability Of Ferrite Multilayer Chip Bead 1-1.Mechanical Performance

No	ltem	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right	Test device shall be soldered on the substrate
		conditions must not damage	Substrate Dimension: 100x40x1.6mm
		the terminal electrode and the	Deflection: 2.0mm
		ferrite	Keeping Time: 30sec
			*For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate
			Oscillation Frequency: 10 to 55 to 10Hz for 1min
			Amplitude: 1.5mm
			Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min
		More than 75% of the terminal	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		electrode should be covered	Solder Temperature: 260±5°C
		with solder.	Immersion Time: 10±1sec
		Impedance : within ±30% of	
		initial value	
1-1-4	Solder ability	The electrodes shall be at	Pre-heating: 150°C, 1min
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		solder coating	Solder Temperature: 245±5°C (Pb-Free)
			Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination	Test device shall be soldered on the substrate,
		Chip	then apply a force in the direction of the arrow.
		F F	Force : 5N
			Keeping Time: 10±1sec
		Mounting Pad	

No	Item	Specification		Test Method		
1-2-1	-2-1 Temperature Cycle Appearance: No damaç		One cycle:			
		Impedance: within±30% of	Step	Temperature (°ℂ)	Time (min)	
		initial value	1	-55±3	30	
			2	25±2	3	
			3	125±3	30	
			4	25±2	3	
			Total: 100c	cycles		
			Measured a	after exposure in the room cor	ndition for 24hrs	
1-2-2 Humidity Resistance			Temperatu	re: 40±2°ℂ		
Relative Humidity: 90 ~ 95% /			umidity: 90 ~ 95% / Time: 100	0hrs		
			Measured a	after exposure in the room cor	ndition for 24hrs	
1-2-3	High		Temperature: 125±3℃ / Relative Humidity: 0%			
	Temperature Resistance		Applied Current: Rated Current /Time: 1000hrs Measured after exposure in the room condition			
1-2-4	Low		Temperature: -55±3°C			
	Temperature Resistance		Relative Humidity: 0% / Time: 1000hrs			
			Measured a	after exposure in the room cor	ndition for 24hrs	





Lead-Free(LF)標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heating	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T ~ 150°C	150°C ~ 200°C	Above 217°C	260±5°C	Peak Temp.~150℃
標準時間 Time spec.	-	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	-
實際時間 Time result	~	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	-

NOTE:

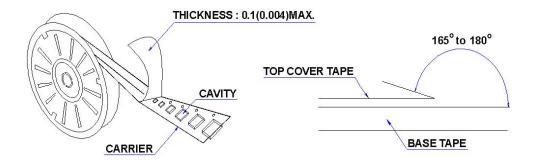
- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow
- 3. Products can only be soldered with reflow



9 Packaging:

9.1 Packaging -Cover Tape

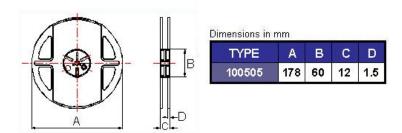
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



9.2 Packaging Quantity

TYPE	PCS/REEL	
100505	10000	

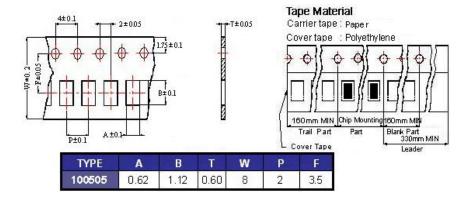
9.3 Reel Dimensions



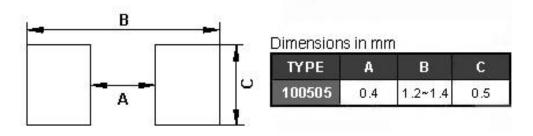


9 Packaging:

9.4 Tape Dimensions in mm



10 Recommended Land Pattern:



11 Note:

- 1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)
- 5. The moisture sensitivity level (MSL) of products is classified as level 1.



